



## **UTEK Places Repeat Order for Applied Materials' Producer System; High-Performance, Cost-Effective Technology Key to Multiple System Repeat Buy**

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Business Editors/High-Tech Writers

SANTA CLARA, Calif.--(BUSINESS WIRE)--Aug. 26, 1999--Applied Materials, Inc. announced today that UTEK Semiconductor Corp. of Taiwan, part of the UMC (United Microelectronics Corp.) Group and one of the world's largest foundry companies, has placed a multiple-system, repeat order for Applied Materials' Producer(TM) CVD (chemical vapor deposition) technology. Shipments of the Producer system began to UTEK's facility in Hsin-Chu, Taiwan, early this year.

Eric Hsu, manager of Thin Film Process at UTEK, said, "Applied Materials' Producer system is ideal for foundries like ours, because it combines extremely high productivity with outstanding technical performance and process flexibility. Installation and qualification of the Producers has gone very quickly, so we've been able to move the systems into production in a short time. These systems are now running in production with excellent reliability." UTEK will use the systems to deposit TEOS (tetraethylorthosilicate), silane and dielectric anti-reflective coating (DARC(TM)) films for manufacturing DRAM and logic devices.

Introduced by Applied Materials in 1998, the Producer system features a revolutionary new platform architecture that combines the throughput benefits of Twin Chamber(TM) wafer handling with the advantages of single-wafer process technology in a simple and exceptionally reliable system design. The system offers a major improvement in productivity as well as reduced facilities cost and a small system footprint. Configured with up to three Twin Chamber CVD modules, a maximum of six wafers can be processed simultaneously, achieving system throughput of more than 120 wafers per hour. To simplify system design without sacrificing the flexibility and control of single-wafer processing, each Twin Chamber set uses the same pumps, mass flow controllers and gas delivery components.

Each Twin Chamber module uses Applied Materials' Remote Clean(TM) technology to remove deposited byproducts with minimal damage to process kit hardware, resulting in drift-free processing. This unique "soft" clean process creates virtually no global-warming perfluorocompounds (PFC) and enables significant reduction in chamber clean frequency for very high equipment uptime and availability.

"UMC and UTEK have aggressively advanced their technical capabilities and are in the top tier of semiconductor companies in the world. This repeat order demonstrates their confidence in the cost-effective, advanced technology the Producer system offers for their foundries, where higher yields, lowest cost and maximum asset utilization are key requirements," said Kevin Fairbairn, general manager of Applied Materials' PECVD Product Unit.

According to Dataquest, a market research firm, the market for (non-high-density) plasma-enhanced CVD (PECVD) dielectric films totaled \$426 million in 1998, and is projected to grow to \$656 million by 2003. Dataquest reports that Applied Materials the leading supplier of both dielectric and metal CVD systems.

Applied Materials, Inc. is a Fortune 500 global growth company and the world's largest supplier of wafer fabrication systems and services to the global semiconductor industry. Applied Materials is traded on the Nasdaq National Market System under the symbol "AMAT." Applied Materials' web site is <http://www.appliedmaterials.com>.

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